**TELID® 382.i**

**RFID inclination data logger 13.56MHz**
- semi passive sensor data logger
- 3D inclination measurement based on earth acceleration
- non flexible hard TAG, package Q54
- mountable on metal or nonmetal objects
- contactless data communication based on ISO14443

RFID Sensor TELID® devices are an integral part of microsensys iID® system solution. These devices are very useful for wireless sensor applications in industrial solutions, especially in maintenance processes and in building industry. TELIDs are operating optimal with microsensys standard RFID stationary and mobile reader devices.

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**RFID Technology:** RFID system TELID®300
- **Chip Type:** iID-L
- **Carrier Frequency:** 13.56 MHz
- **Communication Rate:** 106 kbps
- **Communication Distance:** 0 ... 20 mm depending on reader antenna and environmental conditions

**Data Memory:** EEPROM read write type
- **Static Memory:** parameters, calibration data, manufacturer OTP, ID-No
- **Recording Capacity:** 256 kbit or 1 Mbit
- **Data Recording Capacity:** 8 bit per channel and sample

**Real Time Clock:**
- **Temperature Sensor:** semiconductor sensor
- **Working Temperature:** -40°C ... +85°C
- **Resolution:** 0.5 K not calibrated

**Accelerometer Sensor:** MEMS sensor, 3D acceleration (x, y, z-axis)
- **Measure Range:** +2.0 g ... -2.0 g
- **Frequency Range:** 0 ... 10 Hz
- **Resolution:** 12 bit theoretical 1 mg

**Application:** 3D inclination data logging, preferably for inclination changing measurements
- **Measure Range:** +45° ... -45°
- **Resolution:** theoretical 0.5° (+1 g ... -1 g) x-y axis sensor optional

**Temperature Sensor:**
- ** informs inclination measurements
- **Working Temperature:** -40°C ... +85°C
- **Resolution:** up to 2 years depending on using conditions

**Temperature Sensor:**
- **Application:** preferably for inclination changing measurements
- **Resolution:** theoretical 0.5° (+1 g ... -1 g) x-y axis sensor optional

**Temperature Sensor:**
- **Temperature Sensor:** semiconductor sensor
- **Working Temperature:** -40°C ... +85°C
- **Resolution:** 0.5 K not calibrated

**Operating Modes:**
- **SLEEP, ZERO SETING or ACTIVE LOGGING**

**Measure Modes:**
- **LOGGING: STOP FULL**
- **Nmax programmable**

**Basic Functions:**
- **programming of parameters, item information and measure modes**
- **set start time, read header, read data memory**

**Parameters:**
- **zero reference at installation, calibration data and event limits (optional)**
- **Sample Time:** 1 min ... 59 min, programmable

**Battery:** LiMnO2, 125 mAh
- **Life Time:** up to 2 years depending on using conditions

**Working Temperature:**
- **Temperature Sensor:** semiconductor sensor
- **Working Temperature:** -35°C ... +85°C
- **Storage Temperature:** -40°C ... +90°C (short time 100°C) recommended 25°C

**Dimensions:**
- **54 x 40 mm², thickness max. 4.5 mm**

**Protection Class:**
- **IP 67**

**Marking:**
- laser printed product type on top, optional unique ID-No adhesive on metal (reduced Comm.Dist.) or nonmetal objects

**Mounting Instruction:**
- **adhesive on metal (reduced Comm.Dist.) or nonmetal objects**

**Appropriate RFID Reader:**
- **PEN reader** with RS232TTL, USB or Bluetooth
- **HEAD reader** with RS232TTL, CAN or USB for industrial application
- **POCKETwork** with USB or Bluetooth

**Software:**
- **TELID381.i application software for mobile devices** based on TELIDsoft 5.0, Windows

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**TELID®382.i**

**Type :**
- **TELID®382.i**
- **TELID®382.111.00**
- **TELID®382.111.00**
- **TELID®382.111.10**

**Memory Capacity:**
- **256k**
- **1M**
- **1M**

**Max. 3D-Samples:**
- approx. 8000
- approx. 15000
- approx. 1000

**Max. T-Samples:**
- approx. 15000
- approx. 1000
- approx. 100

**Max. Events:**
- approx. 256k or 1 Mbit

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